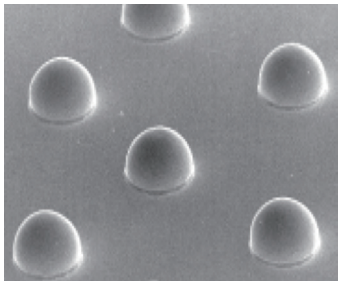
SQ工法
SQ Soldering Process

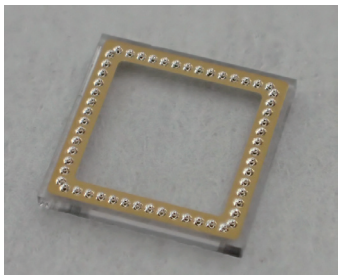
Direct Printing of AuSn Solder

特長 Features

◆組成安定したピュアなAuSnはんだの施工が可能
Pure AuSn soldering with stable material composition
◆ドット状、ライン状、描画等の自由なパターン形成が可能
Flexible pattern forming in dots, lines, drawings etc.,
◆微細パターンへの施工が可能
Precise & Fine pattern forming
◆はんだボリュームの調整が容易
Easy adjustment of solder volume
◆レジスト無しでパターン作製が可能
"Resist" is not required for Pattern forming
◆フラックスフリーのためリフロー後の洗浄が不要
Not need in Cleaning after reflowing owning to Flux-free
◆組成が安定している事により、濡れ性のバラツキを低減
Reduce variation of Wettability due to compositional stability
◆WaferのAuパターンが施された部分へのアライメントが可能
Alignment along with Au pattern on wafer surface

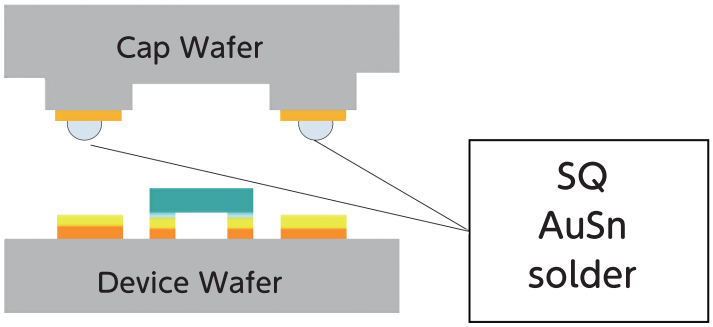


Magnified SEM picture


SQ solder for Glass Lid

用途例 Use case

◆ウエハボンディング
Wafer bonding
◆リング状封止枠 (ガラスリッド)
Ring shaped sealing frame (Glass Lid)
◆ダイボンディング
Die-Bonding
◆バンプ
Bump



Wafer bonding

特性 Characteristics

Solder material	AuSn Eutectic Solder
Ball diameter (dot diameter)	90-380μmΦ (approx.100-450μmΦ)
Print thickness	Approx. 80-250μm
Measurement accuracy	±10μm

Available size	Square measure : 2~8 inch Height : 20 mm (Workable custom made beyond above)
Position accuracy	Distance from Target ±50μm
Surface material	Au plate, Au/Ni plate

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